

## N- and P-Channel 40-V Power MOSFET

### GENERAL DESCRIPTION

The LT4565 is the N- and P-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits where high-side switching, and low in-line power loss are needed in a very small outline surface mount package.

### FEATURES

- $R_{DS(ON)} \leq 40m\Omega @ V_{GS}=10V$  (N-Ch)
- $R_{DS(ON)} \leq 45m\Omega @ V_{GS}=4.5V$  (N-Ch)
- $R_{DS(ON)} \leq 54m\Omega @ V_{GS}=-10V$  (P-Ch)
- $R_{DS(ON)} \leq 60m\Omega @ V_{GS}=-4.5V$  (P-Ch)
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability

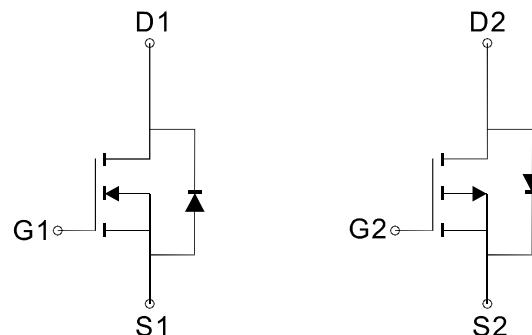
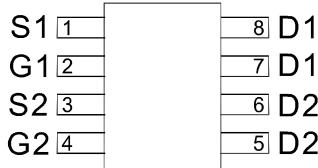
### APPLICATIONS

- Power Management
- DC/DC Converter
- LCD TV & Monitor Display inverter
- CCFL inverter

### PIN CONFIGURATION

(SOP-8)

Top View



### Absolute Maximum Ratings ( $T_A=25^\circ C$ Unless Otherwise Noted)

Parameter	Symbol	N-Channel		P-Channel		Unit
		10 secs	Steady State	10 secs	Steady State	
Drain-Source Voltage	$V_{DSS}$	40		-40		V
Gate-Source Voltage	$V_{GSS}$	$\pm 16$		$\pm 16$		
Continuous Drain Current( $T_j=150^\circ C$ )	$I_D$	6.2	4.9	-5.3	-4.2	A
		4.8	3.8	-4.1	-3.2	
Pulsed Drain Current	$I_{DM}$	25		25		
Avalanche Current	$I_{AS}$	13		16		
Single Pulse Avalanche Energy		8.5		13		mJ
Maximum Power Dissipation	$P_D$	2.5	1.56	2.45	1.52	W
		1.5	0.94	1.47	0.91	
Operating Junction Temperature	$T_J$	-55 to 150				
Thermal Resistance-Junction to Ambient *	$R_{\theta JA}$	50	80	51	82	°C/W
Thermal Resistance-Junction to Case*	$R_{\theta JC}$	49		50		°C/W

\*The device mounted on 1in<sup>2</sup> FR4 board with 2 oz copper

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**Electrical Characteristics (TA = 25°C Unless Otherwise Specified)**

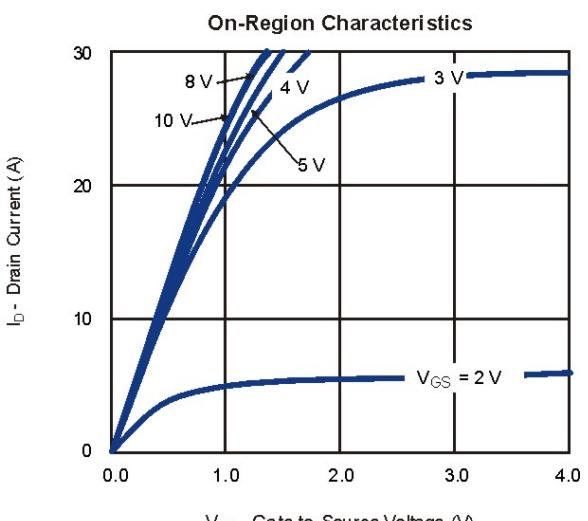
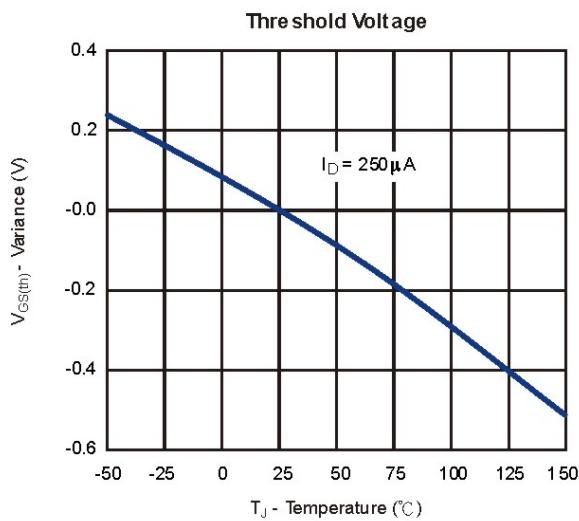
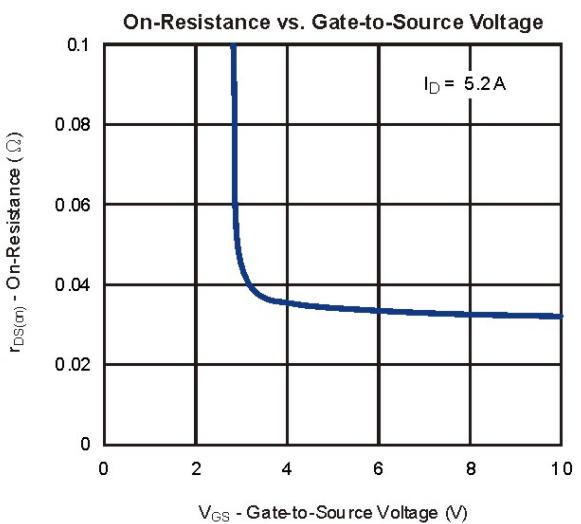
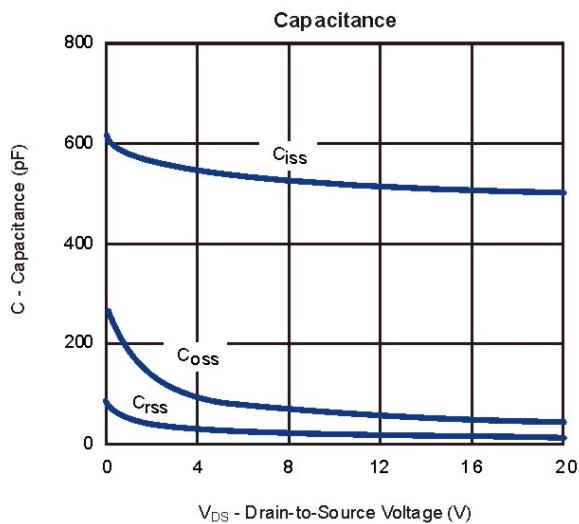
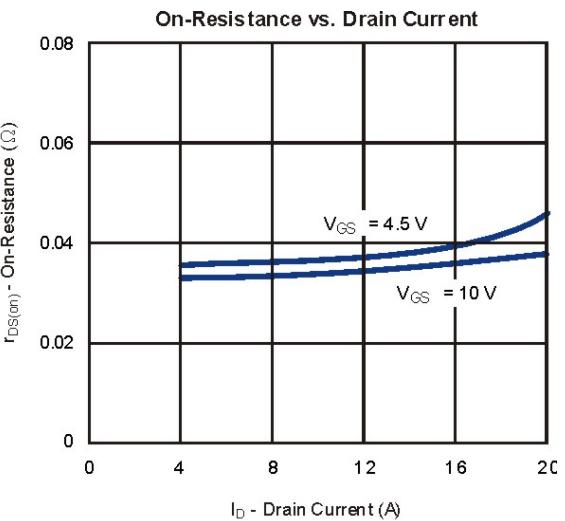
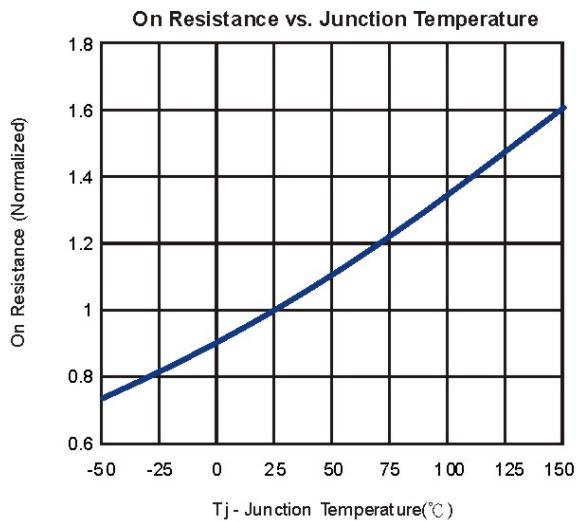
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
<b>STATIC</b>							
V(BR)DSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250 μA V <sub>GS</sub> =0V, I <sub>D</sub> =250 μA	N-Ch P-Ch	40 -40			V
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250 μA V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250 μA	N-Ch P-Ch	0.6 -0.8	0.9 -1.0	1.6 -1.8	V
I <sub>GSS</sub>	Gate Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±16V V <sub>DS</sub> =0V, V <sub>GS</sub> =±16V	N-Ch P-Ch			±100 ±100	nA
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V V <sub>DS</sub> =-40V, V <sub>GS</sub> =0V	N-Ch P-Ch			1 -1	μA
		V <sub>DS</sub> =40V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C V <sub>DS</sub> =-40V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C	N-Ch P-Ch			10 -10	
I <sub>D(ON)</sub>	On-State Drain Current <sup>a</sup>	V <sub>DS</sub> ≥5V, V <sub>GS</sub> = 10V V <sub>DS</sub> ≤-5V, V <sub>GS</sub> = -10V	N-Ch P-Ch	20 -20			A
R <sub>D(S)ON</sub>	Drain-Source On-State Resistance <sup>a</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> = 5.2A V <sub>GS</sub> =-10V, I <sub>D</sub> = -4.5A	N-Ch P-Ch		32 43	40 54	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> = 4.9A V <sub>GS</sub> =-4.5V, I <sub>D</sub> = -3.9A	N-Ch P-Ch		35 48	45 60	
G <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =15V, I <sub>D</sub> =5.2A V <sub>DS</sub> =-15V, I <sub>D</sub> =-4.5A	N-Ch P-Ch		18 13		S
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =1.7A, V <sub>GS</sub> =0V I <sub>S</sub> =-1.7A, V <sub>GS</sub> =0V	N-Ch P-Ch		0.78 -0.79	1.2 -1.2	V
<b>DYNAMIC</b>							
Q <sub>g</sub>	Total Gate Charge	N-Channel V <sub>DS</sub> =20V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =5.2A P-Channel V <sub>DS</sub> =-20V, V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-4.5A	N-Ch P-Ch		8 12		nC
Q <sub>gs</sub>	Gate-Source Charge		N-Ch P-Ch		3.3 5		
Q <sub>gd</sub>	Gate-Drain Charge		N-Ch P-Ch		2.8 5.2		
R <sub>g</sub>	Gate Resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz	N-Ch P-Ch		0.7 4.5		Ω
C <sub>iss</sub>	Input capacitance	N-Channel V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, F=1MHz P-Channel V <sub>DS</sub> =-20V, V <sub>GS</sub> =0V, F=1MHz	N-Ch P-Ch		500 1000		pF
C <sub>oss</sub>	Output Capacitance		N-Ch P-Ch		43 81		
C <sub>rss</sub>	Reverse Transfer Capacitance		N-Ch P-Ch		9.3 22		
t <sub>d(on)</sub>	Turn-On Delay Time	N-Channel V <sub>DD</sub> =15V, R <sub>L</sub> =15Ω I <sub>D</sub> =1A, V <sub>GEN</sub> =10V, R <sub>G</sub> =6Ω	N-Ch P-Ch		8 30		ns
t <sub>r</sub>	Turn-On Rise Time		N-Ch P-Ch		15 12		
t <sub>d(off)</sub>	Turn-Off Delay Time		N-Ch P-Ch		36 62		
t <sub>f</sub>	Turn-On Fall Time		N-Ch P-Ch		2 5		

Notes: a. Pulse test; pulse width ≤ 300us, duty cycle≤ 2%

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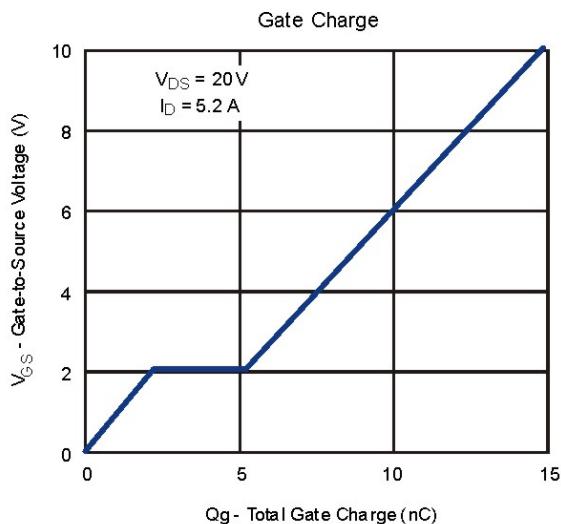
Typical Characteristics ( $T_J = 25^\circ\text{C}$  Noted)

### N-CHANNEL

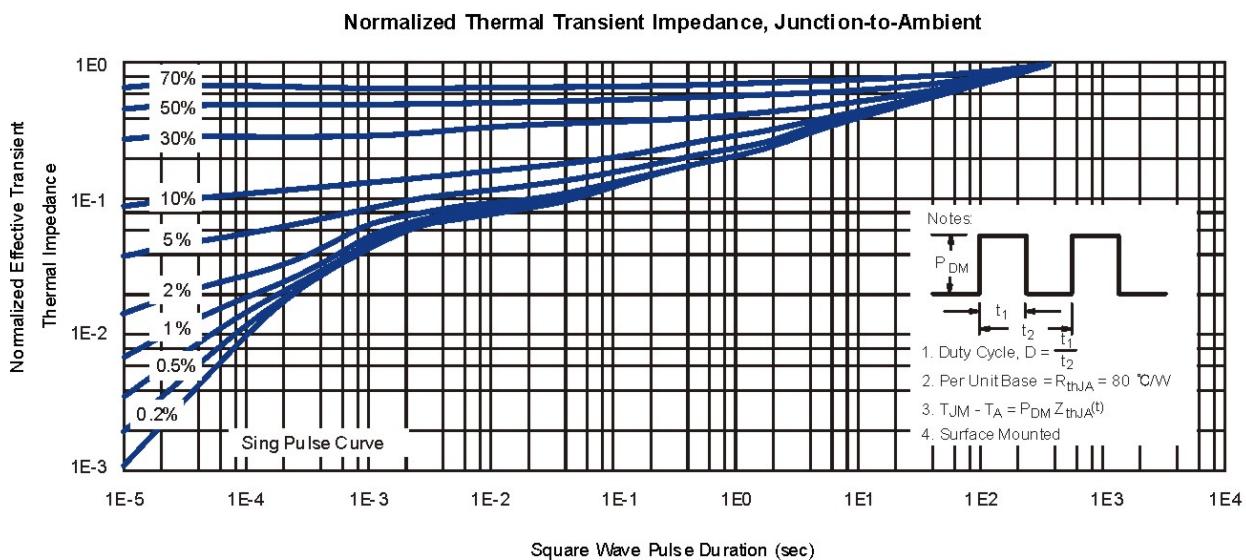
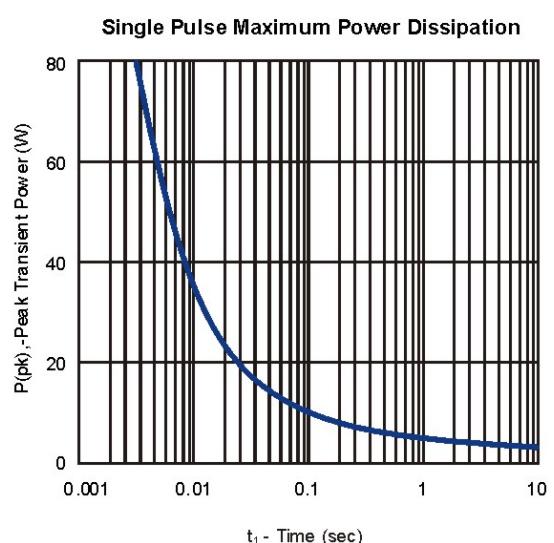
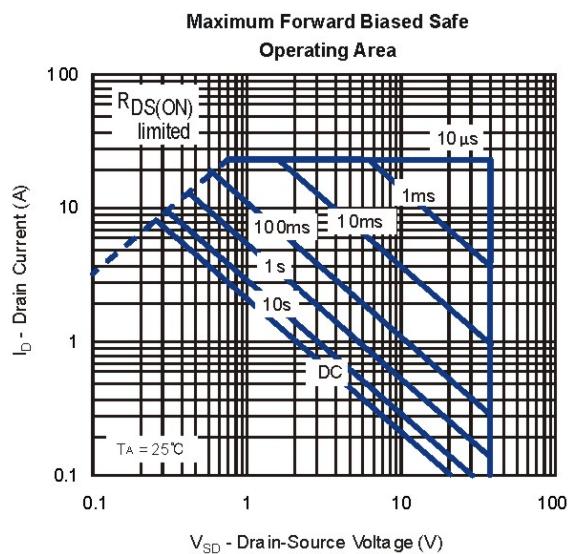
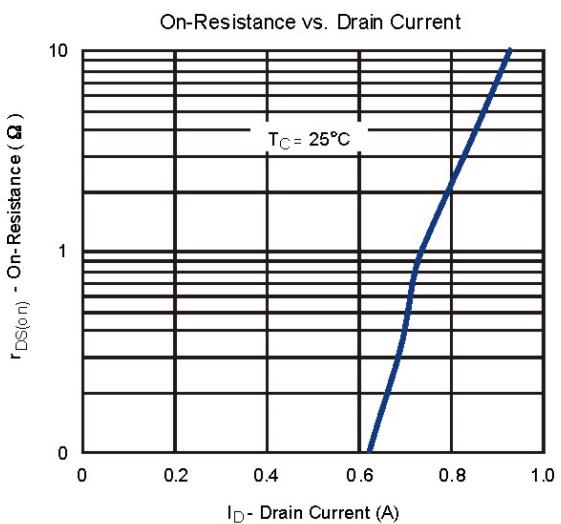


## N- and P-Channel 40-V Power MOSFET

Typical Characteristics ( $T_J = 25^\circ\text{C}$  Noted)



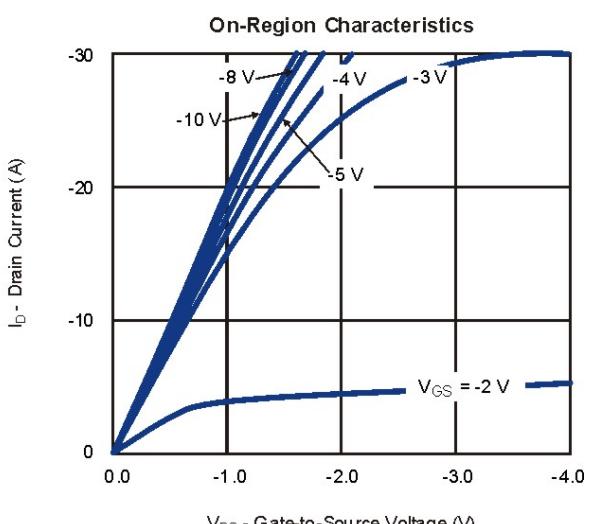
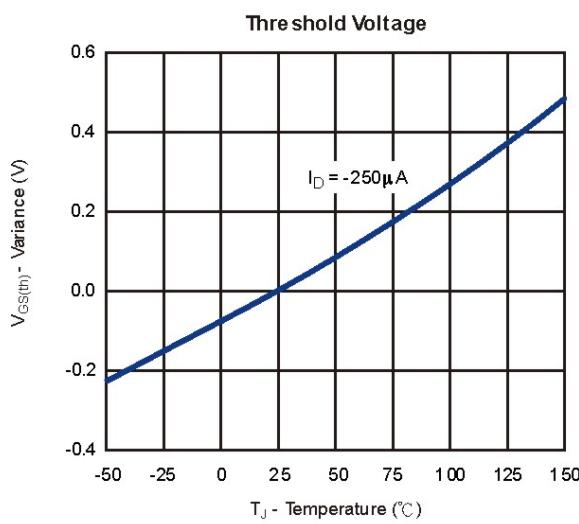
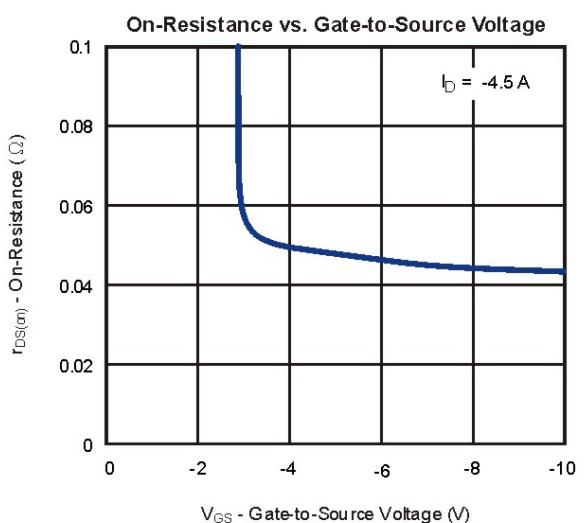
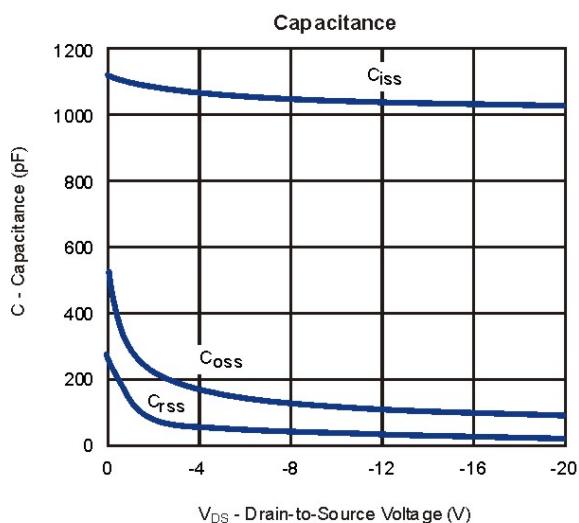
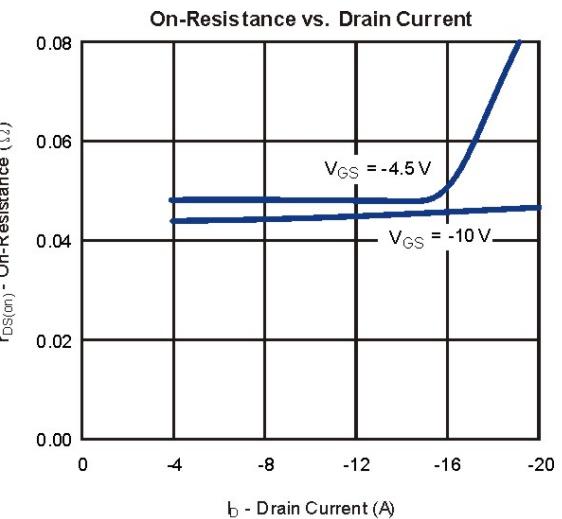
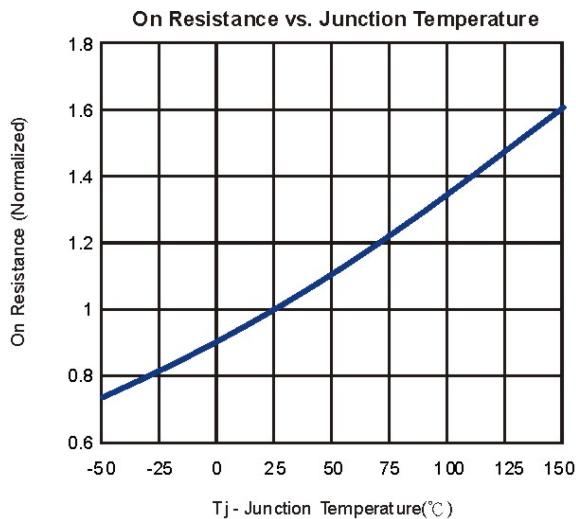
### N-CHANNEL



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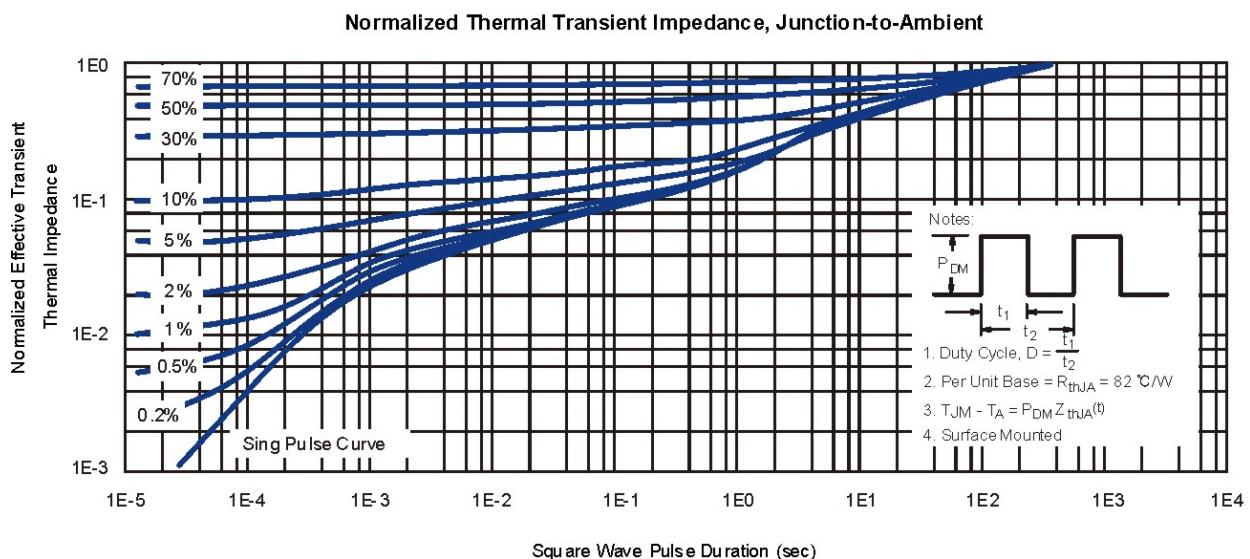
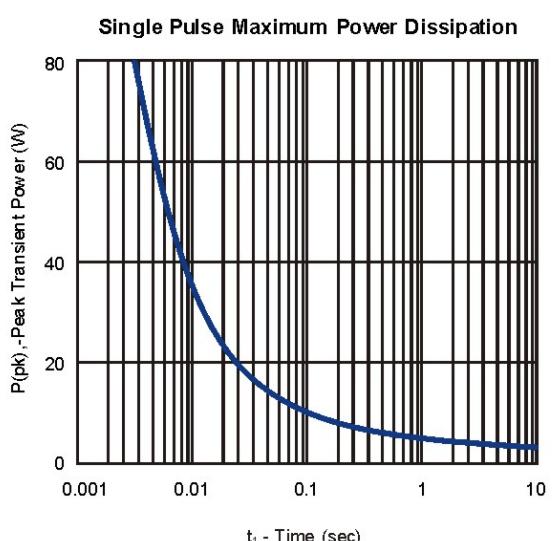
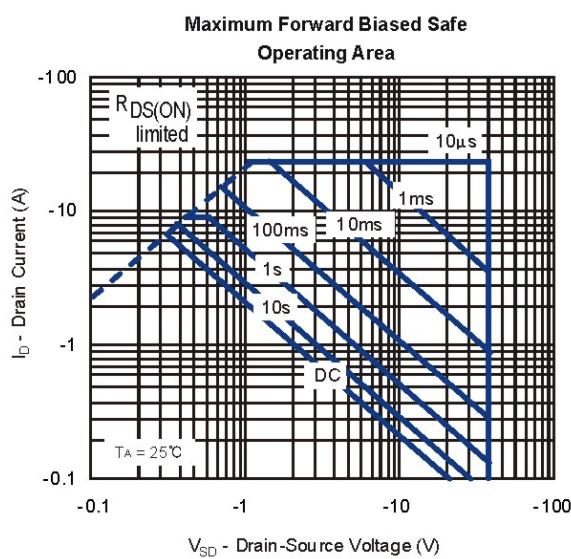
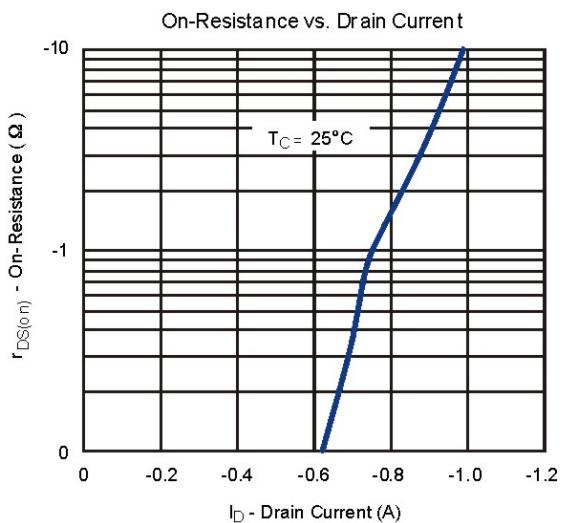
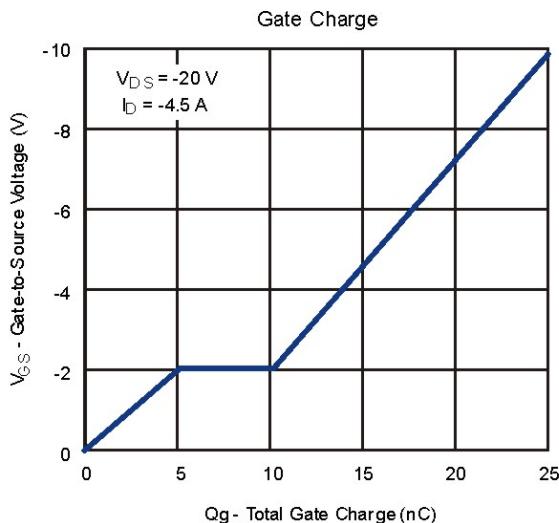
### P-CHANNEL



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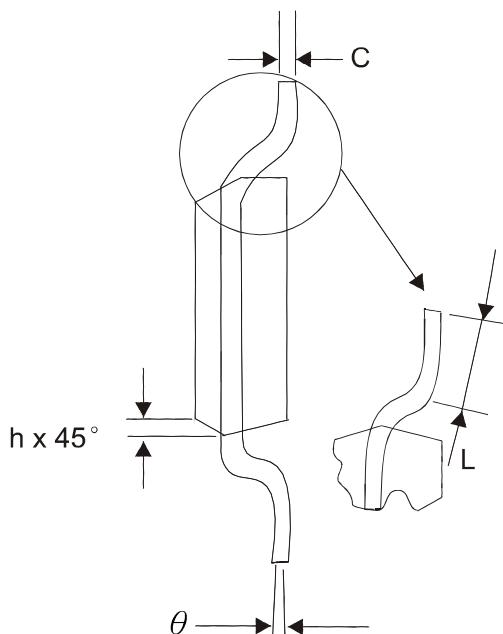
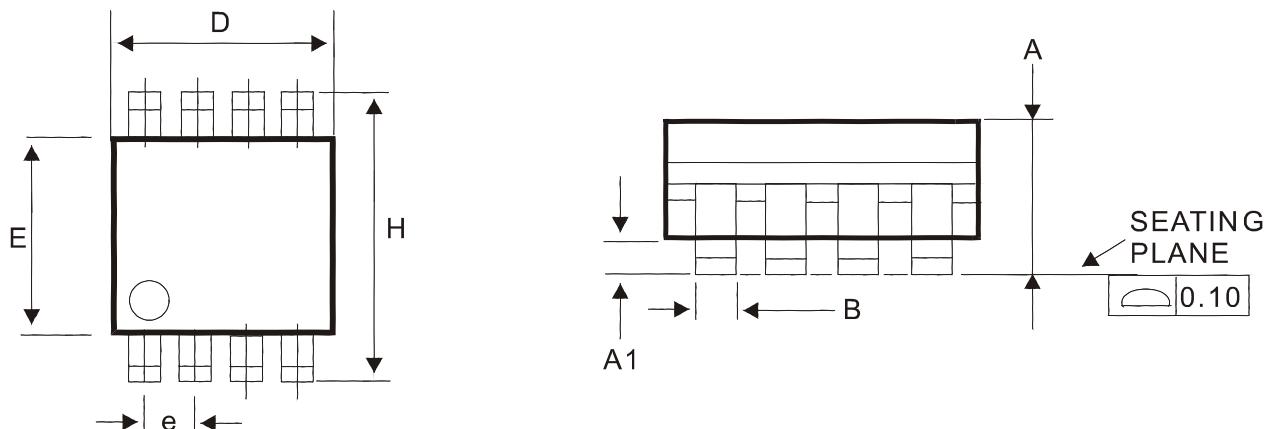
Typical Characteristics ( $T_J = 25^\circ\text{C}$  Noted)

### P-CHANNEL



**N- and P-Channel 40-V Power MOSFET**

**SOP-8 Package Outline**



DIM	MILLIMETERS	
	MIN	MAX
A	1.35	1.75
A1	0.10	0.25
B	0.35	0.49
C	0.18	0.25
D	4.80	5.00
E	3.80	4.00
e	1.27 BSC	
H	5.80	6.20
h	0.25	0.50
L	0.40	1.25
$\theta$	0°	7°